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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/832,160	04/09/2001	Salman Akram	3846.2US(98-0796.2)	8501
24247 75	590 11/12/2004		EXAM	INER
TRASK BRITT			GRAYBILL, DAVID E	
P.O. BOX 2550				
SALT LAKE CITY, UT 84110			ART UNIT	PAPER NUMBER
			2822	<u>-</u>

DATE MAILED: 11/12/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

PTO 90C (Rev 10/03)

	Application No.	Applicant(s)				
	09/832,160	AKRAM ET AL.				
Office Action Summary	Examiner	Art Unit				
	David E Graybill	2822				
The MAILING DATE of this communica Period for Reply	tion appears on the cover sheet wi	th the correspondence address				
A SHORTENED STATUTORY PERIOD FOR THE MAILING DATE OF THIS COMMUNICA  - Extensions of time may be available under the provisions of 3 after SIX (6) MONTHS from the mailing date of this communic  - If the period for reply specified above is less than thirty (30) do  - If NO period for reply is specified above, the maximum statute  - Failure to reply within the set or extended period for reply will, Any reply received by the Office later than three months after earned patent term adjustment. See 37 CFR 1.704(b).	ATION. 7 CFR 1.136(a). In no event, however, may a recation. ays, a reply within the statutory minimum of thirt by period will apply and will expire SIX (6) MON by statute, cause the application to become AB	eply be timely filed  y (30) days will be considered timely.  THS from the mailing date of this communication.  ANDONED (35 U.S.C. § 133).				
Status						
1) Responsive to communication(s) filed on <u>30 August 2004</u> .						
	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claims		•				
4)⊠ Claim(s) <u>1-9 and 12-34</u> is/are pending in the application.						
4a) Of the above claim(s) 4.9 and 23-34 is/are withdrawn from consideration.  5) Claim(s) is/are allowed.  6) Claim(s) 1-3,5-8 and 12-22 is/are rejected.  7) Claim(s) is/are objected to.						
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Application Papers	•					
9) The specification is objected to by the E 10) The drawing(s) filed on <u>09 April 2001 art</u> Examiner.		cepted or b)⊠ objected to by the				
Applicant may not request that any objection	n to the drawing(s) he held in abeyan	ce See 37 CFR 1 85(a)				
Replacement drawing sheet(s) including the	e correction is required if the drawing(	s) is objected to. See 37 CFR 1.121(d).				
Priority under 35 U.S.C. § 119						
12) ☐ Acknowledgment is made of a claim for a) ☐ All b) ☐ Some * c) ☐ None of:	foreign priority under 35 U.S.C. §	119(a)-(d) or (f).				
1. Certified copies of the priority do						
2. Certified copies of the priority do						
3. Copies of the certified copies of t		received in this National Stage				
application from the International  * See the attached detailed Office action for	, , , , , , , , , , , , , , , , , , , ,	and the same of th				
See the attached detailed Office action to	or a list of the certified copies not t	received.				
Attachment(s)						
Notice of References Cited (PTO-892)     Notice of Draftsperson's Patent Drawing Review (PTO-	4) Interview S	ummary (PTO-413)				
<ol> <li>Notice of Draftsperson's Patent Drawing Review (PTO-3) Information Disclosure Statement(s) (PTO-1449 or PTO Paper No(s)/Mail Date <u>1 page</u>.</li> </ol>	948) Paper No(s 0/SB/08) 5) Notice of In 6) Other:	)/Mail Date formal Patent Application (PTO-152) 				

A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 8-30-4 has been entered.

The drawings are objected to as failing to comply with 37 CFR 1.84(p)(4) because, in Figure 1, reference characters 10 and 18 designate the same part, in Figures 1A, 6B and 6C, reference characters 110, 118 and 126 designate the same part, in Figure 8A, reference characters 210 and 218 designate the same part, in Figure 8D, reference characters 210' and 218' designate the same part, in Figure 9A, reference characters 310 and 318 designate the same part, and in Figures 10A and 10B, reference characters 410 and 418 designate the same part.

Also, The drawings are objected to as failing to comply with 37 CFR 1.84(p)(4) because each reference character 18 and 118 has been used to designate multiple different parts.

To further clarify, 37 CFR 1.84 (q) instructs, "Lead lines are those lines between the reference characters and the details referred to. . . . They must originate in the immediate proximity of the reference character and extend to the feature indicated." 37 CFR 1.84 (r) instructs, "Arrows may be used at

the ends of lines, provided that their meaning is clear, as follows: (1) On a lead line, a freestanding arrow to indicate the entire section towards which it points."

In the drawing objection, the reference characters identified as designating the same part are improperly associated with lead lines having freestanding arrows pointing to the same sections, and each reference character identified as being used to designate multiple different parts is improperly associated with lead lines which both extend to indicated features and which indicate an entire section toward which a freestanding arrow points.

A proposed drawing correction or corrected drawings are required in reply to the Office action to avoid abandonment of the application.

Information on current drawing correction practice is available at <a href="http://www.uspto.gov/web/offices/pac/dapp/opla/preognotice/moreinfoamdt">http://www.uspto.gov/web/offices/pac/dapp/opla/preognotice/moreinfoamdt</a>

Prac.htm The objection to the drawings will not be held in abeyance.

In the rejections infra, generally, reference labels are recited only for the first recitation of identical claim elements.

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

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(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claims 1-3, 5-8 and 12-20 are rejected under 35 U.S.C. 102(e) as being anticipated by Hashimoto (6255737).

At column 1, lines 38-53; column 1, line 66 to column 2, line 6; column 4, line 63 to column 8, line 20; and column 10, line 52 to column 12, line 8, Hashimoto discloses a method for fabricating a chip-scale package. comprising: positioning a preformed polymeric film 64 including at least one aperture 64a that extends substantially longitudinally therethrough over a semiconductor device with the at least one aperture in substantial alignment with a corresponding bond pad 62 of the semiconductor device; and inherently selectively introducing conductive material 68 into the at least one aperture following the positioning; adhering the preformed polymeric film to the semiconductor device; defining the at least another aperture through the preformed polymeric film; wherein the defining is effected before the positioning, wherein the introducing comprises bonding the conductive material to the corresponding bond pad, wherein the introducing comprises depositing the conductive material onto the preformed polymeric film and within the at least one aperture, wherein the depositing comprises physical. vapor depositing "sputtering" the conductive material, wherein the

introducing is effected after the positioning; forming at least one contact 20 at an end of the conductive material, opposite the semiconductor device; placing a conductive structure 26 adjacent the at least one contact; applying solder 26 to the at least one contact; positioning at least one conductive trace 58 on the preformed polymeric film and in communication with the conductive material; forming at least one contact in communication with the conductive trace; placing a conductive structure adjacent the at least one contact; applying solder to the at least one contact; and placing the preformed polymeric film on at least a portion of a peripheral edge of the semiconductor device; and placing polymeric material 28 at least laterally adjacent the conductive structure.

To further clarify the disclosure of positioning a preformed polymeric film including at least one aperture, it is noted that the film including the at least one aperture is preformed relative to the introducing step because it is formed in advance of the introducing step. In any case, the cited disclosure that the film "may have holes formed mechanically by predrilling or similar means, and a positioning process may be used for subsequent alignment on the wafer" is an explicit disclosure that the film is preformed.

To further clarify, Hashimoto discloses selectively introducing conductive material because Hashimoto discloses introducing conductive

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material by inherently making a choice of when and where to introduce the material.

To further clarify the disclosure of placing the preformed polymeric film on at least a portion of a peripheral edge of the semiconductor device, it is noted that in the embodiment of the "Sixth Basic Art" the film is placed on the entire wafer 60 including the edge of the device 1 before dicing.

Claims 21 and 22 are rejected under 35 U.S.C. 103(a) as being unpatentable over Hashimoto as applied to claim 17, and further in combination with Jacobs (6294407).

Hashimoto does not appear to explicitly disclose placing a conductive elastomer over at least one conductive structure, and placing another conductive structure in contact with the conductive elastomer, opposite the at least one conductive structure.

Nonetheless, at column 5, line 61 to column 6, line 46, and column 14, line 44 to column 15, line 2, Jacobs discloses placing a conductive (thermally) elastomer 106 over at least one conductive structure 104, and placing another conductive structure 112a in contact with the conductive elastomer, opposite the at least one conductive structure.

Furthermore, it would have been obvious to combine the disclosures of Jacobs and Hashimoto because it would enable external electrical connection and cooling.

Applicant's amendment and remarks filed 8-3-4 have been fully considered, are addressed by the rejections supra, and are further addressed infra.

Applicant traverses the drawing objections because, allegedly, the distances between the drawings and the lead lines renders the drawings compliant.

This traversal is respectfully traversed because the distances between the drawings and the lead lines is not sufficient to render clear the meaning of the lead lines.

Also, applicant submits, "neither reference character 18 nor reference character 118 has been used to designate anything other than a carrier substrate." This submission is deemed unpersuasive because, as elucidated in the objection, "each reference character identified as being used to designate multiple different parts is improperly associated with lead lines which both extend to indicated features and which indicate an entire section toward which a freestanding arrow points." Therefore, the reference characters 18 and 118 associated with lead lines which each extend to indicated features of the carrier substrate appear to designate the indicated features, while the same reference characters associated with lead lines with freestanding arrows appear to designate the entire carrier substrate.

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Applicant also contends that Hashimoto does not disclose placing polymeric material 28 at least laterally adjacent the conductive structure 26 because, allegedly, "the description of Hashimoto is limited to forming 'outermost layer[s] (protective layer[s]),' which partially surround conductive structures."

This contention is respectfully deemed unpersuasive because the alleged disclosure of Hashimoto is not incompatible with the claimed limitation disclosed by Hashimoto.

For information on the status of this application applicant should check PAIR: Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Alternatively, applicant may contact the File Information Unit at (703) 308-2733. Telephone status inquiries should not be directed to the examiner. See MPEP 1730VIC, MPEP 203.08 and MPEP 102.

Any other telephone inquiry concerning this communication or earlier communications from the examiner should be directed to David E. Graybill at (571) 272-1930. Regular office hours: Monday through Friday, 8:30 a.m. to 6:00 p.m.

The fax phone number for group 2800 is (703) 872-9306.

David E. Graybill Primary Examiner Art Unit 2827

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D.G. 9-Nov-04

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